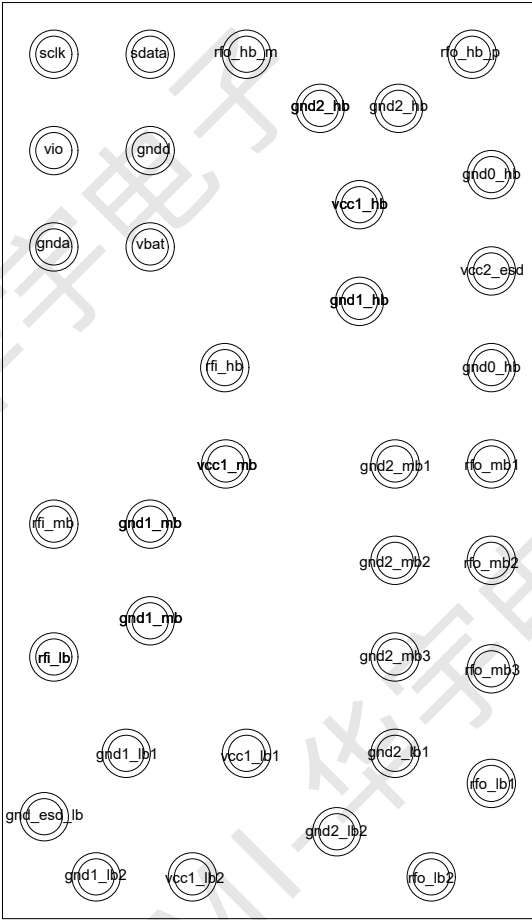


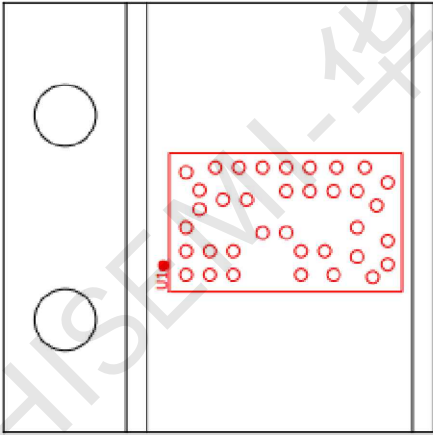
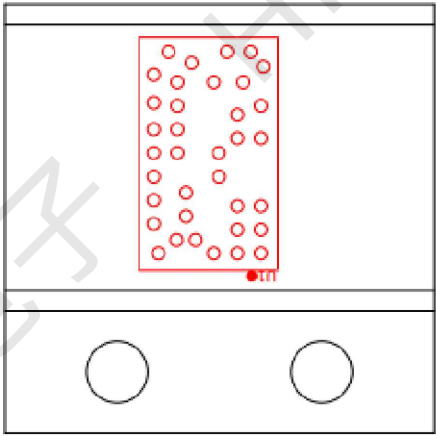
芯片背面图（Bump朝下）

样品验证，禁止量产！



WTR正面图:

载盖带图（Bump朝下）:



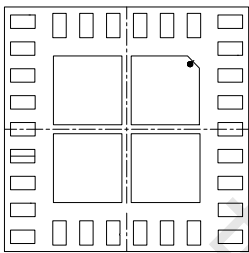
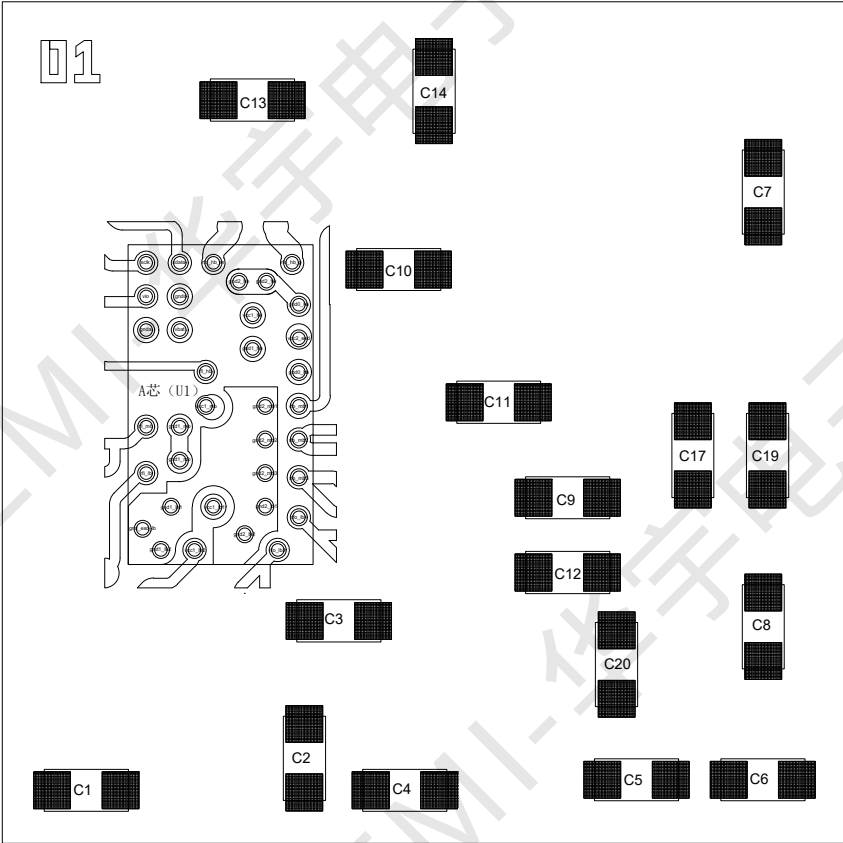
样品验证，禁止量产！

NO.	Item	tags	Reference	value	package	KD P/N	Quantity
1	电容	C1/C3	NA	01005 100nF±10%	01005		2
2	电容	C2	NA	01005 12pF±5%	01005		1
3	电容	C4	NA	01005 8.2pF±0.25pF	01005		1
4	电容	C5	NA	01005 6.8pF±0.1pF	01005		1
5	电容	C6	NA	01005 11pF±5%	01005		1
6	电容	C7/C10 /C19	NA	01005 1.0nF±10%	01005		3
7	电容	C8/C13 /C17/C20	NA	01005 100pF±5%	01005		4
8	电容	C9	NA	01005 6.0pF±0.1pF	01005		1
9	电容	C11	NA	01005 4.7pF±0.1pF	01005		1
10	电容	C12	NA	01005 6.8pF±0.1pF	01005		1
11	电容	C14	NA	01005 1.6pF±0.1pF	01005		1
12	基板	/	FCLGA22L (040040) 1240002	基板	/		1
13	锡膏	/	/	F590 SnCu0.7-89M4	/		/
SMT 元器件总计							17

 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram	客户代码 Customer No.		1240		线图号 Drawing No.		HY-PX-1240-002 A		页码 Page 3 / 4	
			产品名称 Product Type		GH0231A2-LHAA		封装外型 PKG Type		FCLGA30L (4.0X4.0X0.7-P0.44)	
助焊剂 Flux	/	/	/	/	/	塑封料型号(绿色环保) Compound Type (Green)			基板编码 Substrate No.	
TACFlux026S	/	/	/	/	/	首选(PREFERRED): G311ACC 备选(Optional):			FCLGA22L (040040) 1240002	
客户图号 Customer drawing NO.										

样品验证，禁止量产！

PIN1

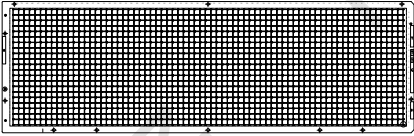


PIN1

注意：

1. 后切割切割道宽度为0.2mm.

底部示意图

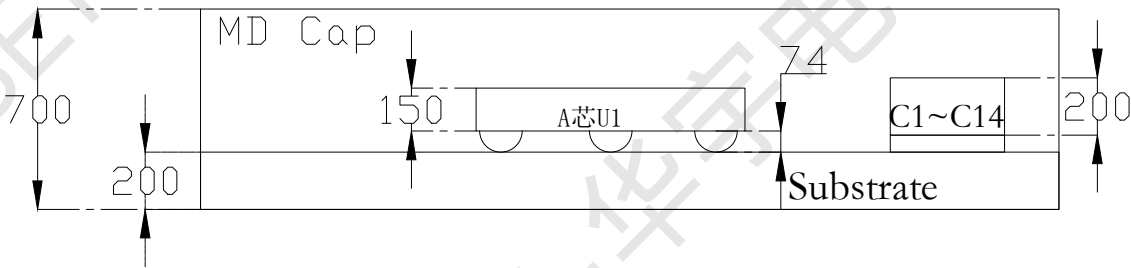
框架传送方向（装片）： L/F Direction (D/A)：（三圆孔朝上）				实物图： Chip photo:				特殊说明 Special Instructions：				
												

序号	芯片名称	芯片尺寸 (带切割道)	晶圆尺寸 Wafer Diameter (inch)	芯片厚度	Wafer material	Bump Size (um)	Bump Compositio n/ Height (um)	Min. Bump Pitch(um)	Bump Structure	Pad S/M Opening of Substrate(MIN)	Min Substrate Bump Pad Size (um)	Bump Type	No. of Bump
A芯 (U1)	LA03-U03	1580*940(μ m²) 62.20*37.00 (mil²)	12	150um	SI (CUP)	84×84	74(Cu43+Ni 3+SnAg28)	130	1P1M	1067X1680	110×110	Pillar Bump	36
拟制 Prepared by				制图日期 Create Date		2025/9/9		生效日期 Effective Date				客户确认签字/盖章: Customer Signature	
研发审核 R&d check				产品工程审核 Product engineering check				批准 Approved by					

*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

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	产品名称 Product Type	GH0231A2-LHAA		封装外型 PKG Type	FCLGA30L (4.0X4.0X0.7-P0.44)	

样品验证，禁止量产！



拟制 Prepared by		制图日期 Create Date	2025/9/9	生效日期 Effective Date		客户确认签字/盖章: Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

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